








APPLICABLE STANDARD					
Rating	Operating Temperature Range	-40 °C to 140 °C <sup>(1)</sup>	Storage Temperature Range	-10 °C to 60 °C <sup>(2)</sup>	
	Voltage	125 V AC <sup>(3)</sup>	Storage Humidity Range	Relative humidity 60% max (Not dewed)	
	Current	0.5 A	Operating Humidity Range	Relative humidity 85% max (Not dewed)	
SPECIFICATIONS					
ITEM		TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION					
General Examination		Examined visually and with a measuring instrument.	According to the drawing.	x	x
Marking		Confirmed visually.		x	x
ELECTRICAL CHARACTERISTICS					
Contact Resistance		Measured at 100 mA MAX.(DC or 1000Hz)	65mΩ MAX.	x	—
Insulation Resistance		Measured at 250 V DC.	1000 MΩ MIN.	x	—
Voltage Proof		375 V AC applied for 1 min.	No flashover or breakdown.	x	—
MECHANICAL CHARACTERISTICS					
Mating and Unmating Forces		Measured with an applicable connector.	Mating Force: 50 N MAX. Unmating Force: 5.5 N MIN.	x	—
Mechanical Operation		Mated and unmated 10 times.	①Contact Resistance : 75mΩ MAX. ②No damage, cracks or looseness of parts.	x	—
Vibration		Frequency 50~100 → 100~150 → 150~300Hz Acceleration 98 → 98~294 → 294 m/s <sup>2</sup> 1 cycle 3 min 3 h for 3 axial directions <sup>(4)</sup>	①No electrical discontinuity of more than 1 μs. ②No damage, cracks or looseness of parts.	x	—
Shock		Acceleration 980 m/s <sup>2</sup> , duration of pulse 6 ms at 3 times for 3 axial directions.		x	—
ENVIRONMENTAL CHARACTERISTICS					
Damp Heat (Steady state)		Exposed at 60±2 °C, 90 ~ 95 %, 1000 h.	①Contact Resistance : 75mΩ MAX. ②Insulation Resistance : 1000 MΩ MIN.  ③No damage, cracks or looseness of parts.	x	—
Rapid Change of Temperature		Temperature -40 → +140 °C Time 30 → 30 min. under 1000 cycles. (Relocation time to chamber : within 2~3 MIN)		x	—
Cold		Exposed at -40°C, 1000 h	①Contact Resistance : 75mΩ MAX. ②No damage, cracks or looseness of parts.	x	—
Dry Heat		Exposed at 140°C, 1000 h		x	—
Sulfur Dioxide		Exposed at 40±2°C, 80±5%RH, 25±5ppm  for 96 h.	Contact Resistance : 75mΩ MAX.	x	—
Resistance to Soldering Heat		1)Reflow soldering : Peak TMP : 260°C MAX Reflow TMP: 220°C MIN for 60sec 	No deformation of case of excessive looseness of the terminal.	x	—
Solderability		Soldered at solder temperature 240±3°C for immersion duration, 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	x	—
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
	1	DIS-F-00016361	TK. ABE	HH. SHINDO	20221215
Notes <sup>(1)</sup> Include temperature rise caused by current-carrying. <sup>(2)</sup> "STORAGE" means a long-term storage state for the unused product before assembly to PCB. <sup>(3)</sup> The creepage distance conforms to IEC 60664-1. Voltage effective value: 32V AC, Pollution Degree: 2 <sup>(4)</sup> Amplitude between connector mounting part and PCB is 0.05mm MAX.			APPROVED	HH. SHINDO	20200422
			CHECKED	KN. SHIBUYA	20200422
			DESIGNED	TK. ABE	20200422
			DRAWN	TK. ABE	20200422
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-376630-00-00
	SPECIFICATION SHEET		PART NO.	FX26-50P-1SV	
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL0576-1005-0-00	 1/1